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The claims on appeal read as follows:

1. A leadframe/stabilizer for use with semiconductor devices, comprising:
 - (a) an electrically conductive leadframe having a central semiconductor die-receiving region and a plurality of leadframe leads extending outwardly from said central die-receiving region; and
 - (b) a stabilizer extending partially along the length of and on each side of said leadframe leads to improve leadframe planarity, said stabilizer including:
 - (i) a die pad mount integral with and forming a part of said stabilizer disposed beneath said central semiconductor die-receiving region for retaining a semiconductor die thereon.
2. The leadframe/stabilizer according to Claim 1, wherein said stabilizer and die pad mount is made of an insulating material.
3. The leadframe/stabilizer according to Claim 1, wherein said stabilizer and die pad mount is made of a plastic material.
4. The leadframe/stabilizer according to Claim 1, wherein said stabilizer and die pad mount is made of a ceramic material.
5. The leadframe/stabilizer according to Claim 1, wherein said die pad mount has a recess in one surface into which a semiconductor die is mounted.

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6. A leadframe stabilizer for use with semiconductor devices, comprising:

(a) an electrically conductive leadframe having a central semiconductor die-receiving region and a plurality of leadframe leads extending outwardly from said central die-receiving region; and

(b) a stabilizer extending partially along the length of and on each side of said lead leadframe leads to improve leadframe planarity, said stabilizer including:

(i) a die pad mount integral with and forming a part of said stabilizer disposed beneath said central semiconductor die-receiving region for retaining a semiconductor die thereon;

(ii) a recess in one surface of said die pad mount; and

(c) a semiconductor die mounted in said recess.

7. The leadframe/stabilizer according to Claim 6, wherein said stabilizer is made of an insulating material.

8. The leadframe/stabilizer according to Claim 1, wherein said stabilizer is made of a plastic material.

9. The leadframe/stabilizer according to Claim 1, wherein said stabilizer is made of a ceramic material.

10. A method for stabilizing the leads of a lead frame and providing a semiconductor die mount pad, comprising the steps of:

(a) providing a leadframe having a central semiconductor die-receiving region and a plurality of leadframe leads extending outwardly from said central die-receiving region;

(b) providing a stabilizer, said stabilizer having a die pad integral therewith and disposed beneath said central semiconductor die-receiving region; and

(c) adhering said stabilizer along part of the length and on each side of said leadframe leads to improve leadframe planarity.

11. The method according to Claim 10, including the step of forming a recessed area in the die pad for mounting of a semiconductor die in said recessed area.

12. The method according to Claim 10, wherein said stabilizer is made of an insulating material.

13. The method according to Claim 10, wherein said stabilizer is made of a plastic material.

14. The method according to Claim 10, wherein said stabilizer is made of a ceramic material.